

L Number	Hits	Search Text	DB	Time stamp
1	0	pacholik-robert.in.	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:40
2	0	lidmer-gunnar.in.	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:41
3	138973	printed adj circuit adj board	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:41
4	48432	electroplating	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:42
5	3554	(printed adj circuit adj board) and electroplating	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:42
6	352604	etching	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:42
7	2158	etching and ((printed adj circuit adj board) and electroplating)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:43
8	2822	electrolysis with copper	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:43
9	31	(etching and ((printed adj circuit adj board) and electroplating)) and (electrolysis with copper)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:51
10	63729	copper.clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:51
11	882	(etching and ((printed adj circuit adj board) and electroplating)) and copper.clm.	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:52
12	1097480	organic	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:53
13	439	((etching and ((printed adj circuit adj board) and electroplating)) and copper.clm.) and organic	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:53
14	245157	recycl\$	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:54
15	18	((etching and ((printed adj circuit adj board) and electroplating)) and copper.clm.) and organic) and recycl\$	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:58
16	35240	205/\$.ccls.	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:58
18	13	recycl\$ and (205/\$.ccls. and (printed adj circuit adj board) and electroplating and etching)	USPAT; US-PPGPUB; EPO; JPO; DERWENT	2003/07/30 13:59

17	286	205/\$.ccls. and (printed adj circuit adj board) and electroplating and etching	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/30 14:24
19	485148	waste	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/30 14:25
20	233	(etching and ((printed adj circuit adj board) and electroplating)) and waste	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/30 14:25
21	36	recycl\$ and ((etching and ((printed adj circuit adj board) and electroplating)) and waste)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/30 14:29
22	36	recycl\$ and ((etching and ((printed adj circuit adj board) and electroplating)) and waste)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/30 14:30
23	13	recycl\$ and (205/\$.ccls. and (printed adj circuit adj board) and electroplating and etching)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/30 14:32
24	89	(205/297).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/30 14:36